FIG.1

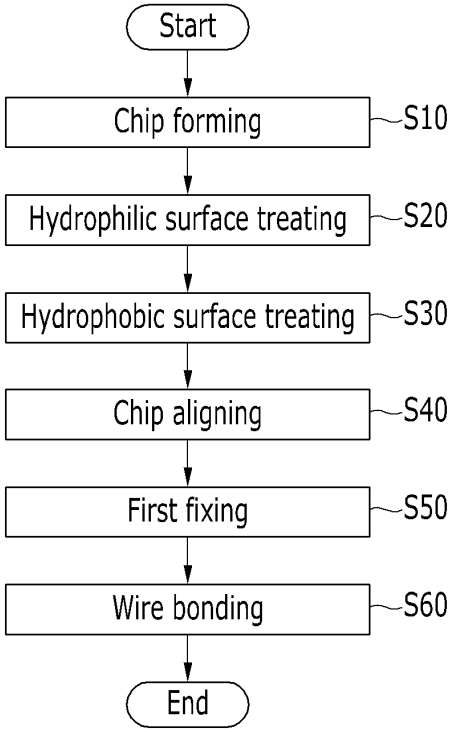


FIG. 2

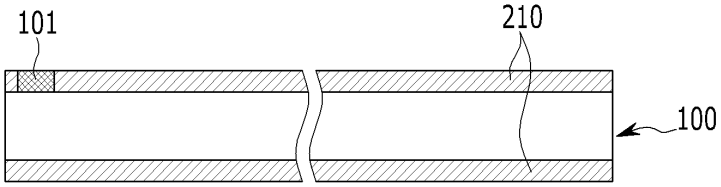


FIG. 3

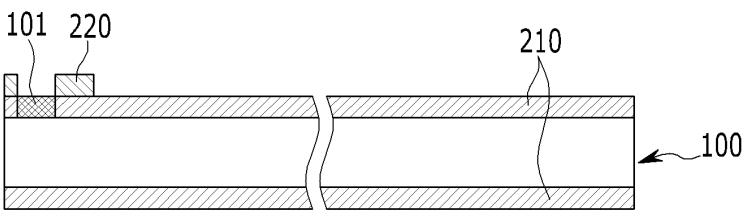


FIG. 4

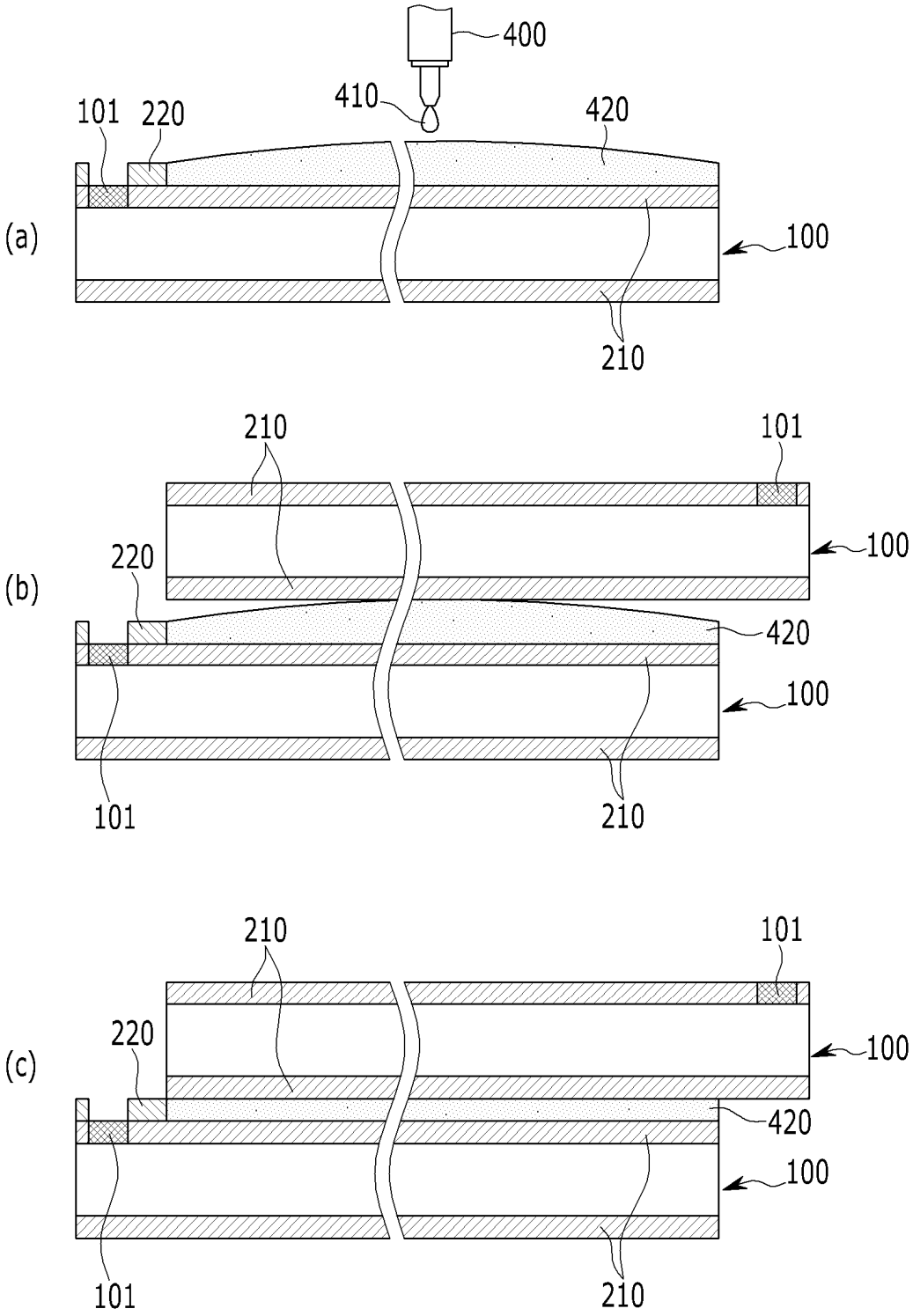

(a)
400
410
101
220
420
100
210
(b)
210
101
220
100
420
100
101
210
(c)
210
101
220
100
420
100
101
210

FIG. 5

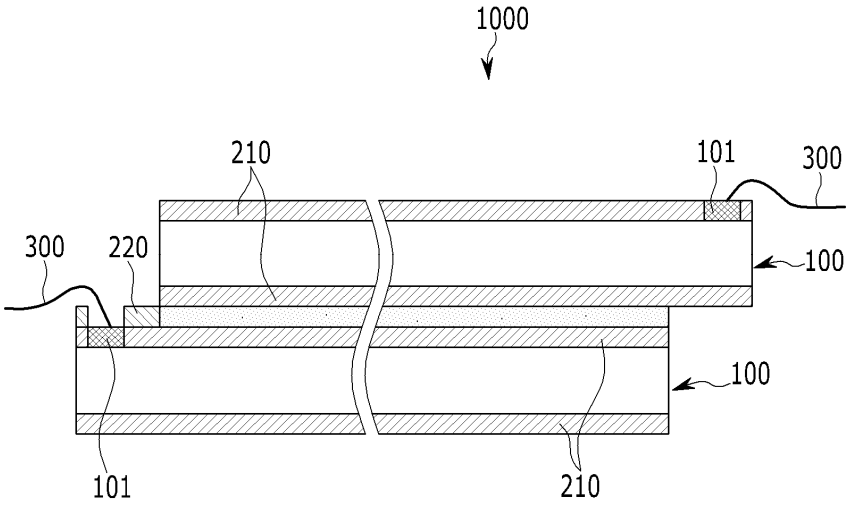

1000
210
101
300
300
220
100
100
101
210

FIG. 6

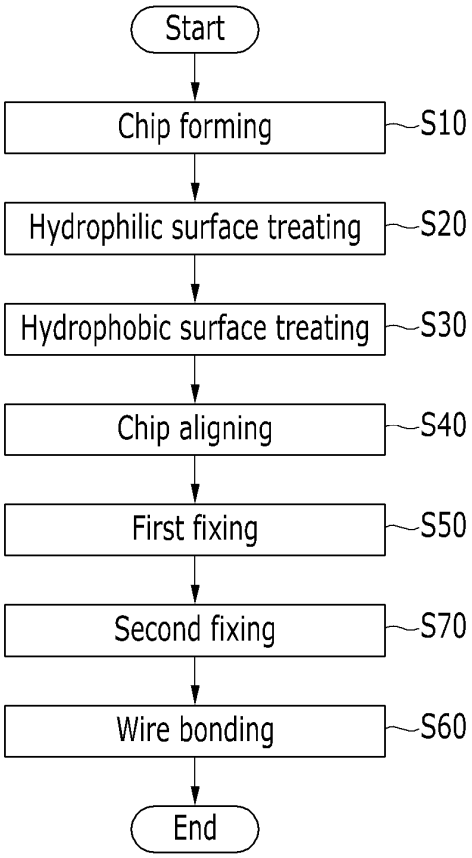

Start
Chip forming
S10
Hydrophilic surface treating
S20
Hydrophobic surface treating
S30
Chip aligning
S40
First fixing
S50
Second fixing
S70
Wire bonding
S60
End

FIG. 7

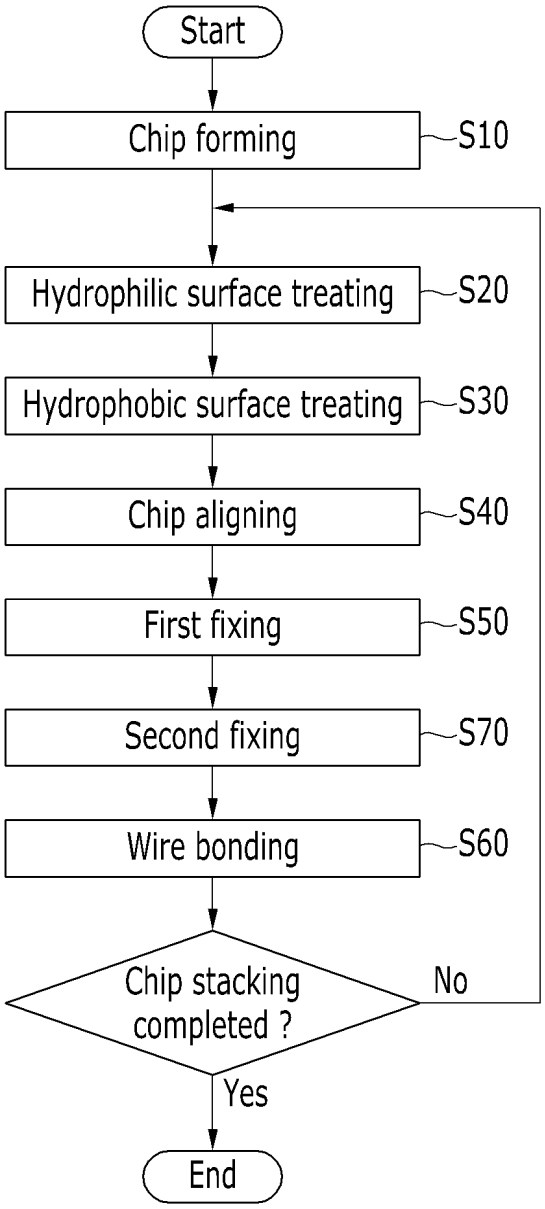

Start
Chip forming
S10
Hydrophilic surface treating
S20
Hydrophobic surface treating
S30
Chip aligning
S40
First fixing
S50
Second fixing
S70
Wire bonding
S60
Chip stacking completed ?
No
Yes
End

FIG. 8

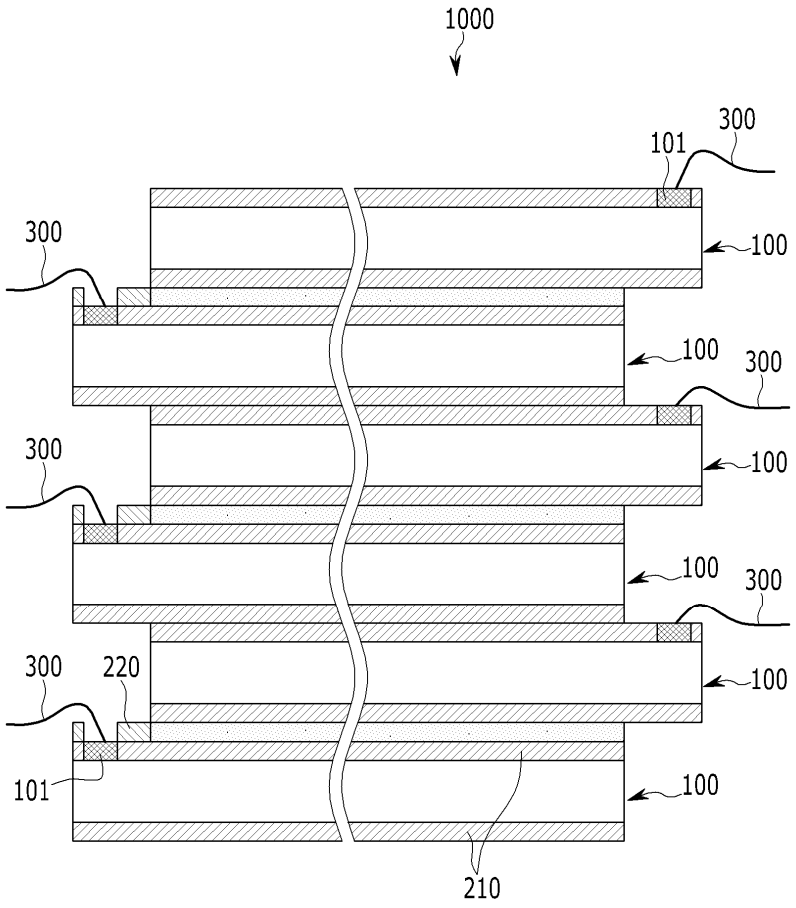
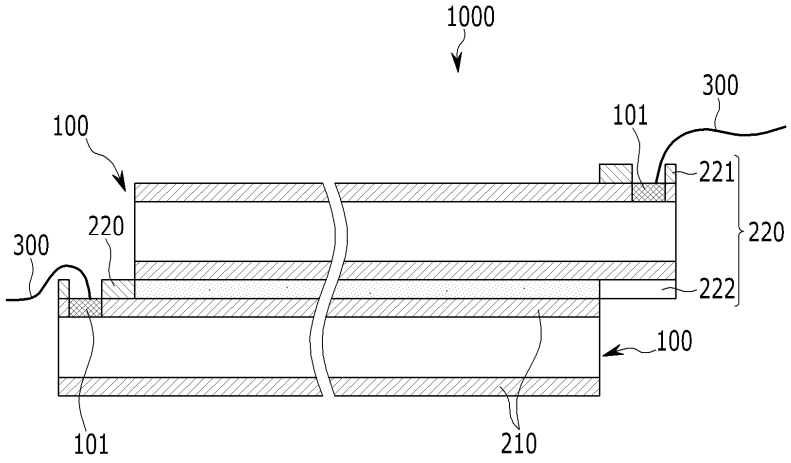

1000
300
101
300
100
100
300
300
100
100
300
300
220
100
101
100
210

FIG. 9


1000
300
101
100
221
220
220
300
222
100
101
210